

Description

The IRLR2905ZPBF uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.



TO-252-2L

General Features

 $V_{DS} = 60V I_{D} = 50 A$

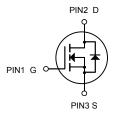
 $R_{DS(ON)}$ < 15m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
IRLR2905ZPBF	TO-252-2L	RLR2905 XXXX	2500

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units		
VDS	Drain-Source Voltage	60	V		
V _G s	Gate-Source Voltage	Gate-Source Voltage ±20			
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	tinuous Drain Current, V _{GS} @ 10V ¹ 50			
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	Continuous Drain Current, V _{GS} @ 10V ¹ 25			
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	Continuous Drain Current, V _{GS} @ 10V ¹ 7.4			
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹ 6		=70°C Continuous Drain Current, V _{GS} @ 10V ¹		А
Ірм	Pulsed Drain Current ²	Pulsed Drain Current ² 90			
EAS	Single Pulse Avalanche Energy ³	Single Pulse Avalanche Energy ³ 39.2			
las	Avalanche Current	nche Current 28			
P _D @T _C =25°C	Total Power Dissipation ⁴ 45		W		
P _D @T _A =25°C	Total Power Dissipation ⁴ 2		W		
Тѕтѕ	Storage Temperature Range -55 to 150		°C		
TJ	Operating Junction Temperature Range	-55 to 150			
R ₀ JA	Thermal Resistance Junction-Ambient ¹	sistance Junction-Ambient ¹ 62 °c			



N-Channel Enhancement Mode MOSFET

ReJc	Thermal Resistance Junction-Case ¹	2.8	°C/W
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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
∆BVpss/∆Tj	V _{DSS} /△T _J BV _{DSS} Temperature Coefficient Reference to 25°C , I _D =1mA			0.057		V/°C
		V _{GS} =10V , I _D =20A		11	15	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A		15	20	$\mathbf{m}\Omega$
V _{GS(th)}	Gate Threshold Voltage		1.2		2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.68		mV/°C
		V_{DS} =48V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	
Ipss	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	uA
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		45		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)			19.3		
Qgs	Gate-Source Charge	V _{DS} =48V , V _{GS} =4.5V , I _D =15A		7.1		nC
Q _{gd}	Gate-Drain Charge			7.6		
T _{d(on)}	Turn-On Delay Time			7.2		
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V ,		50		
T _{d(off)}	Turn-Off Delay Time	R _G =3.3 ,		36.4		ns
T _f	Fall Time	I _D =15A		7.6		
C _{iss}	Input Capacitance			2423		
Coss	Output Capacitance	─		145		pF
Crss	Reverse Transfer Capacitance			97		·
Is	Continuous Source Current ^{1,5}				35	Α
Isм	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			80	Α
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =A , T _J =25°C			1	V
t _{rr}	Reverse Recovery Time			16.3		nS
Q _{rr}	Reverse Recovery Charge	$I_{J}=15A$, $dI/dt=100A/\mu s$, $T_{J}=25^{\circ}C$		11		nC

Note:

- 1.The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=28A
- 4. The power dissipation is limited by 150° C junction temperature 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation



Typical Characteristics

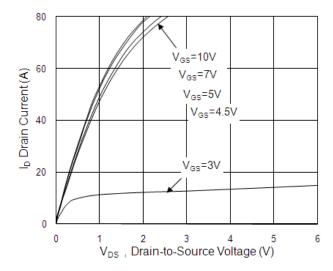


Fig.1 Typical Output Characteristics

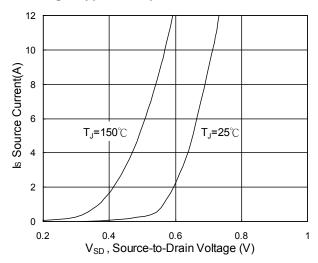


Fig.3 Forward Characteristics of Reverse

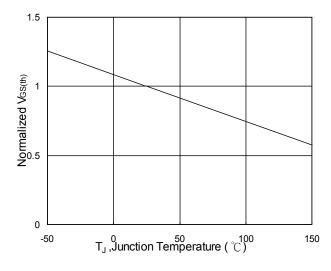


Fig.5 Normalized V_{GS(th)} v.s T_J

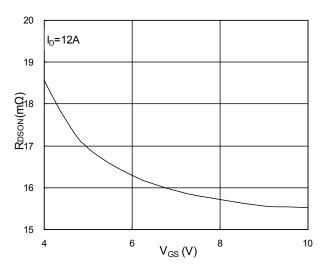


Fig.2 On-Resistance v.s Gate-Source

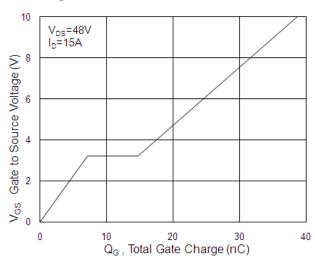


Fig.4 Gate-Charge Characteristics

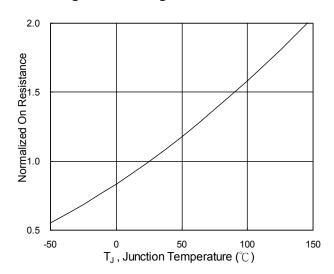


Fig.6 Normalized R_{DSON} v.s T_J

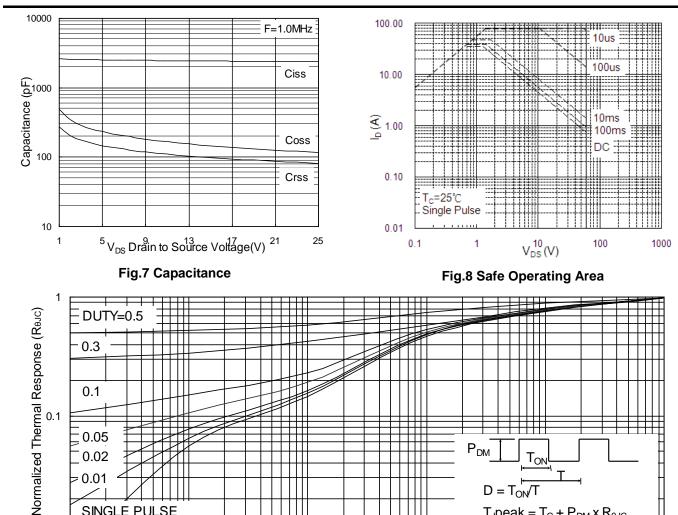
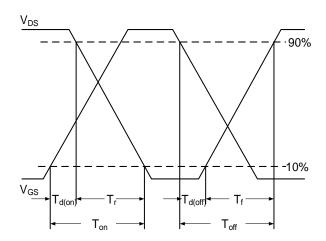


Fig.9 Normalized Maximum Transient Thermal Impedance

t, Pulse Width (s)

0.01

0.001

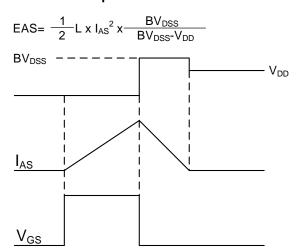


0.0001

SINGLE PULSE

0.01 0.00001

Fig.10 Switching Time Waveform



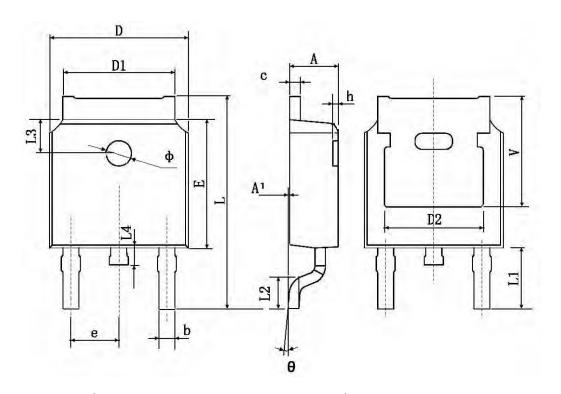
 $T_J peak = T_C + P_{DM} x R_{\theta JC}$

0.1

Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



O mark at	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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